



## **Quik-Pak, Promex Promote Advanced Packaging, Heterogeneous Assembly at Two Industry Events in New York, Washington D.C., Sept. 19-22, 2017**

### **Electronic Packaging Symposium (EPS), International Conference on Silicon Carbide & Related Materials (ICSCRM) Provide Opportunities to Share Advances, Investigate Future Solutions**

Santa Clara, CA – September 19, 2017 – Representatives from [Quik-Pak](#), a provider of microelectronic packaging for complex devices, and its parent company [Promex](#), a provider of IC package development and heterogeneous assembly services, and from its will be on the East Coast September 19- 22, 2017 for two industry events.

At the 29th Annual [Electronic Packaging Symposium \(EPS\)](#), September 19-20 in Niskayuna, New York, Quik-Pak will exhibit information about its new San Diego production line for [overmolded, open-tooled QFN and DFN packages](#). The addition of a wirebonder, molding press and laser marker onsite enables Quik-Pak to expedite packaging for quick-turn engineering builds and volume production.

“Considering that the QFN platform has become the package of choice for single die, multi-die, SiPs and stacked die, it makes sense for us to offer an alternative to going offshore for high-volume production,” said Quik-Pak Global Sales and Marketing Director Casey Krawiec.

Following EPS, Promex and Quik-Pak representatives will participate in the [2017 International Conference on Silicon Carbide and Related Materials \(ICSCRM\)](#) in Washington, D.C. ICSCRM identifies materials and device challenges and discusses applications driving the advancement of SiC technology. The conference is produced by The Materials Research Society (MRS), a member-driven organization of almost 14,000 materials researchers dedicated to the advancement of interdisciplinary materials research.

“ICSCRM’s “moving from niche to mainstream” theme is similar to how we help our customers,” said Promex Director of Sales and Marketing Rosie Medina. “They come to us with a proof of concept for a complex device and we use our materials science-centric experience to specify synergistic IC packaging and assembly processes. The result is a seamless transition from engineering to production.”

#### **ABOUT QUIK-PAK**

Quik-Pak, a division of Promex, provides IC packaging, assembly and wafer preparation services in its ISO 9001:2008-certified, ITAR-registered facility in San Diego, California. The company’s overmolded QFN/DFN premolded air cavity QFN packages are available for prototype to full production needs. Same-day assembly services. More information is available at <http://www.icproto.com> or by calling 858-674-4676.

#### **ABOUT PROMEX**

Founded in 1975, Promex specializes in finding innovative IC packaging and heterogeneous assembly solutions for medical, biotech and automotive and sensor-based microelectronic devices. Located in Silicon Valley, Promex provides onsite engineering development, RoHS-optimized SMT, wafer thinning, dicing, wirebond, flip chip, overmolding and Class 100/Class 1000 cleanrooms. The company is ISO 13485:2003 and ISO 9001:2008 certified and ITAR registered. More information is available at <http://www.promex-ind.com> or by calling 408-496-0222.

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